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SDAS036D - APRIL 1982 - REVISED AUGUST 1995

- 3-State Buffer-Type Outputs Drive Bus **Lines Directly**
- **Bus-Structured Pinout**
- **Package Options Include Plastic** Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

These dual 4-bit D-type latches feature 3-state outputs designed specifically for bus driving. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The dual 4-bit latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs in true form, according to the function table. When LE is low, the outputs are latched. When the clear (CLR) input goes low, the Q outputs go low independently of LE. The outputs are in the high-impedance state when the output-enable (\overline{OE}) input is at a high logic level.

The SN54ALS873B and SN54AS873A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS873B and SN74AS873A are characterized for operation from 0°C to 70°C.

SN54ALS873B, SN54AS873A JT PACKAGE
SN74ALS873B, SN74AS873A DW OR NT PACKAGE
(TOP VIEW)

	•	,	
1CLR 1OE 1D1 [1D2 [1D3 [1D4 [2D1 [2D2 [2D3 [2D4 [2OE]	1 2 3 4 5 6 7 8 9 10 11	18 17 16 15	Vcc 1LE 1Q1 1Q2 1Q3 1Q4 2Q1 2Q2 2Q3 2Q4 2LE
	11	14	·
GND [12	13	2CLR

SN54ALS873B, SN54AS873A ... FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each latch)

	INPU	JTS		OUTPUT
OE	CLR	LE	D	Q
L	L	Х	Х	L
L	Н	Н	Н	н
L	Н	Н	L	L
L	Н	L	Х	Q ₀
Н	Х	Х	Х	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic symbol[†]







[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V ₁	7V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54ALS873B	–55°C to 125°C
SN74ALS873B	0°C to 70°C
Storage temperature range	-65°C to 150°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SNS	54ALS87	'3B	SN74ALS873B		'3B	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



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			SN5	4ALS87	'3B	SN7	4ALS87	'3B	
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX			MAX	UNIT
VIK	V _{CC} = 4.5 V,	II = - 18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	I _{OH} = -0.4 mA	V _{CC} -2			V _{CC} -2			
VOH		I _{OH} = -1 mA	2.4	3.3					V
	V _{CC} = 4.5 V	I _{OH} = -2.6 mA				2.4	3.2		
N		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ
Ц	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.2			- 0.2	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		11	21		11	21	
ICC	V _{CC} = 5.5 V	Outputs low		16	29		16	29	mA
		Outputs disabled		20	31		20	31	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLR low	15		15		
tw	Pulse duration	LE high	10		10		ns
t _{su}	Setup time, data before LE \downarrow		10		10		ns
t _h	Hold time, data after LE \downarrow		7		7		ns



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL R1 R2	c = 4.5 V = 50 pF, = 500 Ω, = 500 Ω, = MIN to			UNIT
			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	
^t PLH	P	Q	2	23	2	14	
^t PHL	D	Q	2	17	2	14	ns
^t PLH		0	8	31	8	22	
^t PHL	LE	Q	8	26	8	21	ns
^t PHL	CLR	Q	6	27	6	20	ns
^t PZH	ŌĒ	0	4	24	4	18	
tPZL	UE	Q	4	23	4	18	ns
^t PHZ	OE	Q	2	12	2	10	ns
tPLZ	UE	Q	2	30	2	15	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V	
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54AS873A	–55°C to 125°C
SN74AS873A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN54AS873A SN74AS873A					
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
IOL	Low-level output current			32			48	mA
TA	Operating free-air temperature	-55		125	0		70	°C



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			SN	54AS87	3A	SN	74AS873	3A	
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = – 18 mA			-1.2			-1.2	V
	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			
VOH		I _{OH} = – 12 mA	2.4	3.2					V
	V _{CC} = 4.5 V	I _{OH} = -15 mA				2.4	3.3		
N/		I _{OL} = 32 mA		0.25	0.5				
V _{OL}	$V_{CC} = 4.5 V$	$I_{OL} = 48 \text{ mA}$					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μA
lj	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
ЧΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
۱ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.5			- 0.5	mA
۱ ₀ ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
		Outputs high		68	110		68	110	
ICC	$V_{CC} = 5.5 V$	Outputs low		67	109		67	109	mA
		Outputs disabled		80	129		80	129	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				S873A	A SN74AS873A		
			MIN	MAX	MIN	MAX	UNIT
. *	w* Pulse duration	CLR low	5		5		
tw*	Pulse duration	LE high	6		5		ns
t _{su} *	Setup time, data before LE \downarrow		2		2		ns
t _h *	Hold time, data after LE \downarrow		4.5		4.5		ns

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS SDAS036D – APRIL 1982 – REVISED AUGUST 1995

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL R1 R2 TA	UNIT			
			SN54A	S873A	SN74AS873A		
			MIN	MAX	MIN	MAX	
^t PLH	D	0	3	12.5	3	9.5	
^t PHL		Q	3	8.5	3	7.5	ns
^t PLH		0	6	15.5	6	13	ns
^t PHL	LE	Q	4	9	4	7.5	
^t PHL	CLR	Q	3	10.5	3	9	ns
^t PZH	ŌĒ	0	2	8	2	6.5	
tPZL	UE	Q	4	11	4	10.5	ns
^t PHZ	OE	Q	2	8	2	7.5	ns
tPLZ	UE	Ŷ	2	8.5	2	7.5	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SDAS036D - APRIL 1982 - REVISED AUGUST 1995





- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device		Package Type	•	Pins	Package Qty		Lead/Ball Finish	•	Op Temp (°C)		Samples
	(1)		Drawing			(2)		(3)		(4)	
84032013A	ACTIVE	LCCC	FK	28	1	TBD	Call TI	Call TI	-55 to 125	84032013A SNJ54ALS 873BFK	Samples
8403201KA	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
8403201LA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Call TI	-55 to 125	8403201LA SNJ54ALS873BJT	Samples
SN74ALS873BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	Samples
SN74ALS873BNT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74ALS873BNTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	Samples
SN74AS873ADW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ADWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ANT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS873BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	Samples
SNJ54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	Samples
SNJ54AS873AFK	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS873AJT	OBSOLETE	CDIP	JT	24		TBD	Call TI	Call TI	-55 to 125		



24-Jan-2013

Orderable Device	Status	Package Type	•	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SNJ54AS873AW	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A :

• Catalog: SN74ALS873B, SN74AS873A

• Military: SN54ALS873B, SN54AS873A

NOTE: Qualified Version Definitions:





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24-Jan-2013

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· · /	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS873BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS873BDWR	SOIC	DW	24	2000	367.0	367.0	45.0

MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



MECHANICAL DATA

MCFP007 - OCTOBER 1994



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a ceramic lid using glass frit.

- D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
- E. Index point is provided on cap for terminal identification only.



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



NT (R-PDIP-T**) 24 pins shown

PLASTIC DUAL-IN-LINE PACKAGE



All integrations are in minimeters. Dimensioning and toil
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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